



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In the application of

Confirmation No. 3064

Hiroaki INOUE et al.

Docket No. 2001_1094A

Serial No. 09/890,455

Group Art Unit 2812

Filed March 12, 2002

Examiner Lynne A. Gurley

ELECTROLESS PLATING LIQUID AND METHOD
OF FORMING INTERCONNECTION USING SUCH
AN ELECTROLESS PLATING LIQUID

AMENDMENT

Assistant Commissioner for Patents,
Washington, D.C.

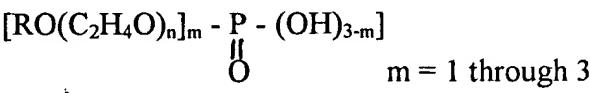
Sir:

Responsive to the Official Action dated December 31, 2002, please amend the above-identified application as follows:

IN THE SPECIFICATION

Page 5, lines 19-25, please replace the paragraph with the following rewritten paragraph:

The electroless copper plating liquid should preferably further contain polyoxyethylene alkylether phosphoric acid, polyoxyethylene alkylether, and a mixture of polyoxyethylene alkylether phosphoric acid and polyoxyethylene alkylether (e.g., RT610 manufactured by Toho Chemical Industry Co., Ltd.), indicated below, at a concentration ranging from 1 to 100 mg/E₃ (polyoxyethylene alkylether phosphoric acid)



(polyoxyethylene alkylether)

RO(C₂H₄O)_nH.

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W/ATTACH
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Mullis

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